

IN THE CLAIMS:

Please cancel Claims 1 - 21, 26, and 37 without prejudice. Please amend Claims 22, 27, 29, 33, 39, and 40 as follows:

1 - 21 (Cancelled)

22. (Currently Amended) A component for use within a semiconductor processing chamber, wherein said component has at least one ceramic surface which has patterned mechanical interlocks formed therein , wherein said patterned mechanical interlocks are undercut into said at least one ceramic surface using a process selected from the group consisting of pattern etching said ceramic surface through a mask using a chemical etchant, patterning etching said ceramic using a thermal etching process, and pattern etching said ceramic using a laser micromachining process which employs a laser system which includes optics for producing a patterned beam, and wherein a sacrificial coating which can be removed essentially without harming said ceramic surface has been applied over said ceramic surface containing said patterned mechanical interlocks.

23. (Original) The component of Claim 22, wherein said ceramic is selected from the group consisting of alumina, quartz, aluminum nitride, silicon carbide, silicon nitride, boron carbide, and combinations thereof.

24. (Cancelled)

25. (Cancelled)

26. (Cancelled)

27. (Currently Amended) The component of Claim 26 22, wherein said sacrificial material is aluminum.
28. (Original) The component of Claim 27, wherein said aluminum layer has a thickness within the range of about 76 μm to about 1.5 mm.
29. (Currently Amended) The component of Claim ~~26~~ 22, wherein said component includes a bond coat layer between said ceramic surface and said sacrificial material layer.
30. (Original) The component of Claim 29, wherein said bond coat layer comprises a material having a coefficient of thermal expansion which is no more than about 20% higher or lower than the coefficient of thermal expansion of said ceramic.
31. (Original) The component of Claim 29, wherein said ceramic comprises alumina, and said bond coat layer comprises a material selected from the group consisting of tantalum, rhenium, molybdenum, chromium, titanium, platinum, nickel, manganese, and combinations thereof.
32. (Original) The component of Claim 31, wherein said bond coat layer comprises tantalum, and said tantalum layer has a thickness within the range of about 7.6 μm to about 38 μm .
33. (Currently Amended) A deposition ring for use within a physical vapor deposition chamber, wherein said deposition ring has at least one ceramic surface which has patterned mechanical interlocks formed therein, wherein said patterned mechanical interlocks are undercut into said at least one ceramic surface using a process selected from the group consisting of pattern etching said ceramic surface through a mask using a chemical etchant, patterning etching

said ceramic using a thermal etching process, and pattern etching said ceramic using a laser micromachining process which employs a laser system which includes optics for producing a patterned beam, and wherein a sacrificial coating which can be removed essentially without harming said ceramic surface has been applied over said ceramic surface containing said patterned mechanical interlocks .

34. (Original) The deposition ring of Claim 33, wherein said ceramic is selected from the group consisting of alumina, quartz, aluminum nitride, silicon carbide, silicon nitride, boron carbide, and combinations thereof.

35. (Cancelled)

36. (Cancelled)

37. (Cancelled)

38. (Currently Amended) The deposition ring of Claim ~~37~~ 33, wherein said sacrificial material is aluminum.

39. (Original) The deposition ring of Claim 38, wherein said aluminum layer has a thickness within the range of about 76 μm to about 1.5 mm.

40. (Currently Amended) The deposition ring of Claim ~~37~~ 33, wherein said deposition ring further includes a bond coat layer between said ceramic surface and said sacrificial material layer.

41. (Original) The deposition ring of Claim 40, wherein said bond coat layer comprises a material having a coefficient of thermal expansion which is no more than about 20% higher or lower than the coefficient of thermal expansion of said ceramic.

42. (Original) The deposition ring of Claim 40, wherein said ceramic comprises alumina, and said bond coat layer comprises a material selected from the group consisting of tantalum, rhenium, molybdenum, chromium, titanium, platinum, nickel, manganese, and combinations thereof.

43. (Original) The deposition ring of Claim 42, wherein said bond coat layer comprises tantalum, and said tantalum layer has a thickness within the range of 7.6 μm to about 38 μm .